

SEARCH REQUEST FORM

Examiner # (Mandatory): 119941 Requester's Full Name: GEORGE NGUYENArt Unit 3723 Location (Bldg/Room#): CP2 11E04 Phone (circle 305 306 308) 0163Serial Number: 08/1960, 431 Results Format Preferred (circle): PAPER DISK E-MAILTitle of Invention UTILITYInventors (please provide full names): SUGI YAMA et al.Earliest Priority Date: 4/13/95

Keywords (include any known synonyms registry numbers, explanation of initialisms):

Is this application involved in litigation?

PAT. No. 5,605,499.

Search Topic:

Please write detailed statement of the search topic, and the concept of the invention. Describe as specifically as possible the subject matter to be searched. Define any terms that may have a special meaning. Give examples of relevant citations, authors, etc., if known. You may include a copy of the abstract and the broadcast or most relevant claim(s).

— no reported litigation —

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 N.A. Sequence A.A. Sequence Structure (#) Bibliographic Litigation Fulltext Procurement Other

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 STN Questel/Orbit Lexis/Nexis WWW/Internet In-house sequence systems (list) Dialog Dr. Link Westlaw Other (specify)

PATNO IS 5605499

Leigh's search

DATE: JUNE 24, 1999
LIBRARY: PATENT
FILE: ALL

Your search request is:
PATNO IS 5605499

Number of PATENTS found with your search request through:
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Your search request has found 1 PATENT through Level 1.
To DISPLAY this PATENT press either the KWIC, FULL, CITE or SEGMENTS key.
To MODIFY your search request, press the M key (for MODFY) and then the ENTER key.

For further explanation, press the H key (for HELP) and then the ENTER key.

LEVEL 1 - 1 PATENT

1. 5,605,499, Feb. 25, 1997, Flattening method and flattening apparatus of a semiconductor device, Sugiyama, Misuo, Ayase, Japan Arai, Hatsuyuki, Ayase, Japan, Speedfam Company Limited, Tokyo, Japan (03)

CORE TERMS: cloth, polishing, wafer, flattening, polished, film, layer, insulating, fluff, pad...

LEVEL 1 - 1 OF 1 PATENT

5,605,499

<=2> GET 1st DRAWING SHEET OF 12

Feb. 25, 1997

Flattening method and flattening apparatus of a
semiconductor device

REISSUE: Reissue Application filed Oct. 29, 1997 (O.G. Sep. 29, 1998) Ex. Gp.:
3203; Re. S.N. 08/960,431

CORE TERMS: cloth, polishing, wafer, flattening, polished, film, layer,
insulating, fluff, pad...

5,605,499 OR 5605499

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SS 1 RESULT (1)

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-1- (LEGSTAT)

PATENT NUMBER	US 5605499 [US5605499]
DOCUMENT TYPE	US-P
ACTION	95.04.13 US/AE-A
	APPLICATION DATA (PATENT)
	{US 421706/95 [95US-421706] 95.04.13}
ACTION	95.05.30 US/AS02
	ASSIGNMENT OF ASSIGNOR'S INTEREST
	SPEEDFAM COMPANY LIMITED 30-3, NISHI-ROKUGO 4-CHOME,
	OTA-KU TOKYO, JAPAN * SUGIYAMA, MISUO : 19950510;
	ARAI, HATSUYUKI : 19950510
ACTION	97.02.25 US/A
	PATENT
ACTION	98.09.29 US/RF
	REISSUE APPLICATION FILED
	971029
UPDATE	9920

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14	1	US5605556/PN
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} no citations for 499 in LITALERT

ACCESSION NUMBER 9839-001036
PATENT NUMBER US5605499
DOCUMENT TYPE A (UTILITY)
OFFICIAL GAZETTE 98.09.29
CODE REA
ACTION REISSUE APPLICATION FILED
SUBJECT HEADING REISSUE APPLICATION FILED

File 345:Inpadoc/Fam.& Legal Stat 1999/UD=9924
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Set Items Description
S1 1 PN=US 5605499

1/9/1

DIALOG(R) File 345:Inpadoc/Fam.& Legal Stat
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12748585

Basic Patent (No,Kind,Date): JP 7297195 A2 951110 <No. of Patents: 002>

PATENT FAMILY:

JAPAN (JP)

Patent (No,Kind,Date): JP 7297195 A2 951110
METHOD AND APPARATUS FOR FLATTENING SEMICONDUCTOR DEVICE (English)
Patent Assignee: SPEEDFAM CO LTD
Author (Inventor): SUGIYAMA MISUO; ARAI HATSUYUKI
Priority (No,Kind,Date): JP 94112091 A 940427
Applic (No,Kind,Date): JP 94112091 A 940427
IPC: * H01L-021/3205; B24B-001/00; B24B-037/04; H01L-021/304
CA Abstract No: ; 124(14)191352C
Derwent WPI Acc No: ; C 96-025435
Language of Document: Japanese

UNITED STATES OF AMERICA (US)

Patent (No,Kind,Date): US 5605499 A 970225
FLATTENING METHOD AND FLATTENING APPARATUS OF A SEMICONDUCTOR DEVICE
(English)
Patent Assignee: SPEEDFAM COMPANY LIMITED (JP)
Author (Inventor): SUGIYAMA MISUO (JP); ARAI HATSUYUKI (JP)
Priority (No,Kind,Date): JP 94112091 A 940427
Applic (No,Kind,Date): US 421706 A 950413
National Class: * 451443000; 451041000
IPC: * B24B-021/18
CA Abstract No: * 124(14)191352C
Derwent WPI Acc No: * C 96-025435
Language of Document: English

UNITED STATES OF AMERICA (US)

Legal Status (No,Type,Date,Code,Text):
US 5605499 P 940427 US AA PRIORITY (PATENT)
JP 94112091 A 940427
US 5605499 P 950413 US AE APPLICATION DATA (PATENT)
(APPL. DATA (PATENT))
US 421706 A 950413
US 5605499 P 950530 US AS02 ASSIGNMENT OF ASSIGNOR'S
INTEREST
SPEEDFAM COMPANY LIMITED 30-3, NISHI-ROKUGO
4-CHOME, OTA-KU TOKYO, JAPAN ; SUGIYAMA,
MISUO : 19950510; ARAI, HATSUYUKI : 19950510
US 5605499 P 970225 US A PATENT
US 5605499 P 980929 US RF REISSUE APPLICATION FILED
(REISSUE APPL. FILED)
971029